

IN THE CLAIMS

Please amend claims 51, 58, and 65, as indicated below.

1-50. (Cancelled)

51. (Currently Amended) A semiconductor die package,
comprising:

an encapsulant body having opposed top and bottom
surfaces and side surfaces vertically between the top and
bottom surfaces;

inner leads each having an inner first and an outer
second end, the first and second ends being within the
encapsulant body;

outer leads each having an inner portion within the
encapsulant body and an outer portion extending outside of the
encapsulant body;

a die paddle within the encapsulant body,

wherein the inner leads and the die paddle are lower
in the encapsulant body than the encapsulated inner
portions of the outer leads, a bottom surface portion of
each of the inner leads and the die paddle is exposed at
the bottom surface of the encapsulant body, and the
unencapsulated outer portion of each of the outer leads
includes a bottom surface portion that is approximately
coplanar with the bottom surface of the encapsulant body

and the exposed bottom surface portions of the die paddle and inner leads; and

a semiconductor die within the encapsulant body, mounted on the inner leads and the die paddle, and electrically coupled to the inner leads and to the inner portion of the outer leads.

52. (Previously Presented) The package of Claim 51, wherein an inner end of the encapsulated inner portion of the outer leads does not extend inwardly beyond the second end of the inner leads.

53. (Previously Presented) The package of Claim 51, wherein an inner end of the encapsulated inner portion of the outer leads extends inwardly beyond the second end of the inner leads.

54. (Previously Presented) The package of claim 51, further comprising an encapsulated layer of an insulative tape coupled across the inner leads and disposed between the inner leads and the semiconductor die.

55. (Previously Presented) The package of claim 51, further comprising an encapsulated layer of an insulative tape

coupled across the inner leads, wherein the inner leads are disposed between the layer of the insulative tape and the semiconductor die.

56. (Previously Presented) The package of claim 51, wherein the inner leads include an encapsulated second bottom surface portion that is adjacent to the exposed bottom surface portion of the inner lead.

57. (Previously Presented) The package of claim 51, wherein the inner leads are planar between the first and second ends.

58. (Currently Amended) A semiconductor die package, comprising:

an encapsulant body having opposed top and bottom surfaces and side surfaces vertically between the top and bottom surfaces;

inner leads each having an inner first end and an outer second end, the first and second ends being within the encapsulant body;

outer leads each having an encapsulated inner portion within the encapsulant body and an unencapsulated outer

portion that extends outward from the side surface of the encapsulant body;

a die paddle within the encapsulant body,

wherein a bottom surface portion of each of the inner leads and the die paddle is exposed at the bottom surface of the encapsulant body, and the unencapsulated outer portion of each of the outer leads is vertically bent so as to have a bottom surface portion that is approximately coplanar with the bottom surface of the encapsulant body and the exposed bottom surface portions of the inner leads; and

a semiconductor die within the encapsulant body, mounted on the inner leads and the die paddle, and electrically coupled to the inner leads and to the inner portion of the outer leads.

59. (Previously Presented) The package of Claim 58, wherein an inner end of the encapsulated inner portion of the outer leads does not extend inwardly beyond the second end of the inner leads.

60. (Previously Presented) The package of Claim 58, wherein an inner end of the encapsulated inner portion of the

outer leads extends inwardly beyond the second end of the inner leads.

61. (Previously Presented) The package of claim 58, further comprising an encapsulated layer of an insulative tape coupled across the inner leads and disposed between the inner leads and the semiconductor die.

62. (Previously Presented) The package of claim 58, further comprising an encapsulated layer of an insulative tape coupled across the inner leads, wherein the inner leads are disposed between the layer of the insulative tape and the semiconductor die.

63. (Previously Presented) The package of claim 58, wherein the inner leads include an encapsulated second bottom surface portion that is adjacent to the exposed bottom surface portion of the inner lead.

64. (Previously Presented) The package of claim 58, wherein the inner leads are planar between the first and second ends.

65. (Currently Amended) A semiconductor die package,
comprising:

an encapsulant body having opposed first and second
surfaces and side surfaces vertically between the first and
second surfaces;

inner leads each having an inner first end and an outer
second end, the first and second ends being within the
encapsulant body;

outer leads each having an encapsulated inner portion
within the encapsulant body and an unencapsulated outer
portion that extends outward from the side surface of the
encapsulant body;

a die paddle within the encapsulant body,

wherein a surface portion of each of the inner leads
is exposed at the first surface of the encapsulant body,
and the unencapsulated outer portion of each of the outer
leads is vertically bent so as to have a surface portion
that is approximately coplanar with one of the first and
second surfaces of the encapsulant body;

a semiconductor die within the encapsulant body, mounted
on the inner leads and the die paddle ~~by an adhesive layer~~,
and electrically coupled to the inner leads and to the inner
end portion of the outer leads.

66. (Previously Presented) The package of Claim 65, wherein an inner end of the encapsulated inner portion of the outer leads does not extend inwardly beyond the second end of the inner leads.

67. (Previously Presented) The package of Claim 65, wherein an inner end of the encapsulated inner portion of the outer leads extends inwardly beyond the second end of the inner leads.

68. (Previously Presented) The package of claim 65, further comprising an encapsulated layer of an insulative tape coupled across the inner leads and disposed between the inner leads and the semiconductor die.

69. (Previously Presented) The package of claim 65, further comprising an encapsulated layer of an insulative tape coupled across the inner leads, wherein the inner leads are disposed between the layer of the insulative tape and the semiconductor die.

70. (Previously Presented) The package of claim 65, wherein the inner leads include an encapsulated second bottom

surface portion that is adjacent to the exposed bottom surface portion of the inner lead.

71. (Previously Presented) The package of claim 65, wherein the inner leads are planar between the first and second ends.

72. (Previously Presented) The package of claim 65, wherein the unencapsulated outer portion of each of the outer leads is bent so as to have a surface portion that is approximately coplanar with the first surface of the encapsulant body.

73. (Previously Presented) The package of claim 65, wherein the unencapsulated outer portion of each of the outer leads is bent so as to have a surface portion that is approximately coplanar with the second surface of the encapsulant body.